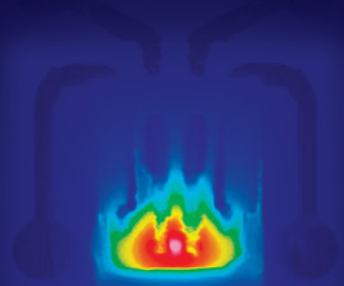




INCERAM

**Thermal Management
Ceramic Packaging Solutions
Optimal Performance
Your Challenging Applications**

and
for
in



THE COMPANY

INCERAM is a technology-driven company with global expertise and strong Indian roots, backed by decades of engineering and business experience and a proven record of successful projects across Europe and Russia.

We are now bringing this well-established production and business model to India, developing advanced local manufacturing to strengthen the country's fast-growing electronics industry.

By combining international know-how with deep local market insight, we provide ready-to-use technologies and highly customized, scalable ceramic packaging solutions. Our expertise spans ceramic machining, metallization, and assembly, serving industries such as automotive, semiconductors, optoelectronics, microwave, aerospace, and defense.

Driven by expertise and innovation, Inceram is redefining industry standards — in India and beyond.

TECHNOLOGICAL EXPERTISE

Advanced Ceramic Processing

- Wide Range of Materials: 96% and 99.6% Al_2O_3 , AlN , Si_3N_4 , ferrite, etc.
- Precision Laser Processing: machining, drilling, cutting, scribing, ablation, marking
- Diamond Dicing and Profiling
- Lapping and Polishing

Custom Glass and Special Material Development

- Technical Glasses and Thick-Film Pastes: synthesis, analysis, development, manufacturing (including those without analogues)
- Thermally Conductive Materials: development and manufacturing of high-performance thermal interface materials
- Development of unique MEMS structures for gas sensing devices

Metallization

- Thick Film Metallization: conductors (Ag , AgPd , AgPt , Au , Ru , Pt), resistors and thermistors (Ru , RuPdAg , Pt), glass coating
- Thin Film Metallization: Cr , V , Ti , NiCr , Ni , Nb , Cu , Al , Au , Pt , Si alloys
- Direct Bonded Copper: special processing, including laser etching
- Electro- and Electroless Plating: Ni , Au , ENIG , ENIG , Ag ; solder masking

Hybrid Assembly

- Die Attach: epoxy, solder
- Wire Bonding: Al , Au , Pt wire; ultrasonic or thermocompression bonding
- Sealing/Encapsulation: epoxy, solder, glass, laser welding

CORE PRODUCTS

Ceramic Components

- Ceramic Thermal Interfaces
- Custom Ceramic Substrates and Components



Thermal Interface Materials

- Thermal pads (silicon, silicon-free, carbon fiber)
- Thermal gels, greases, adhesives



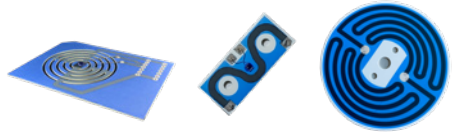
Ceramic Microcircuits & Heatsinks

- Thin Film & Thick Film Microcircuits
- RF/Microwave Microcircuits
- Laser/Photodiode Submounts
- Power LED substrates



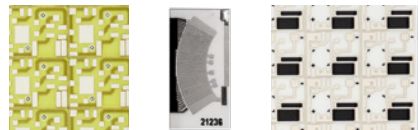
Flat Ceramic Heaters

- Thick Film Microheaters
- Special Heating Elements



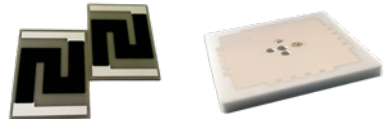
Automotive Components

- Ceramic Sensors & Resistive Elements
- Ceramic PCB's



Special Antennas, Resistors, Resonators

- Ceramic Antennas and Resonators
- Custom Power Resistors, RF Termination Resistors



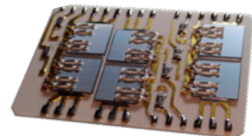
DBC & AMB Substrates

- Custom manufacturing available to meet special requirements that mass producers can not satisfy



Hybrid Assemblies

- Custom Hybrid Micromodules
- Special Power Assemblies



Technical Glasses and Thick-Film Pastes

- Glasses $\text{PbO-V}_2\text{O}_5\text{-P}_2\text{O}_5$; $\text{Bi}_2\text{O}_3\text{-SiO}_2\text{-ZnO}$; $\text{SiO}_2\text{-CaO-Al}_2\text{O}_3$; etc. Glasses of tungsten, titanium, and platinum group compositions
- Special protective, dielectric, conductor and resistor thick-film pastes



**Our team will ensure prompt responses,
provide detailed technical consultation,
and offer the most suitable and cost-effective
manufacturing options**

WE ARE HERE TO ASSIST



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